Noise and Random Telegraph Signals in Nanoelectronic Devices

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Outline

Motivation: Problems Encountered as the Devices Shrink, Frequencies Increase, and Voltages Reduce
Improved Model for 1/f Noise in MOSFETs
Random Telegraph Signals in MOSFETs
Complex RTS

Extraction of trapping parameters using RTS



UTA - Noise Characterization Facilities

- 6' x 6' x 8' Shielded Room
- 3 Spectrum and Signal Analyzers,
 f=1 μHz 20 GHz.

• 3 Cryostats, T= 2 K to 350 K.





- Various Lock-ins, Preamps, System Controllers, Battery Operated Sources etc.
- Optical Equipment
- Computer Software for Modeling



Problems Encountered as the Devices Shrink, Frequencies Increase, and Voltages Reduce

• Signal-to-noise ratio decreases.

 Noise models based on large number of electrons break down.



Quantum effects become dominant.



Signal to Noise Ratio Decreases

For a MOSFET

- •Start from $W=100\mu m$, $L=10\mu m$, $t_{ox}=800$ Å, $N_{SS}=4x10^{10}$ eV⁻¹ cm⁻².
- •Assume scaling factor is *K*.
- •Assume trap and surface state densities remain the same.

$$W \Longrightarrow W/K, L \Longrightarrow L/K, t_{ox} \Longrightarrow t_{ox}/\sqrt{K}$$

Increase in noise level due to the K^{1/2} law chosen for t_{ox}.
Unpredictability of noise level for K>20.

 $\bullet N_{SS}$ is actually a two dimensional Poisson variable.



Single electron, single trap effects.

 N_{SS} =4x10¹⁰ eV⁻¹ cm⁻², W=1µm, L=0.1µm.





Break-down of large-area models for sub-micron channel length.

$$S_{Id}(f) = \frac{kTq^2 I_d \mu_{eff}}{\gamma f L^2 C_{ox}} \left[A \ln \frac{N_O + N^*}{N_L + N^*} + B(N_O - N_L) + \frac{1}{2} C \left(N_O^2 - N_L^2 \right) \right]$$

- $A = N_t (\text{cm}^{-3} \text{ eV}^{-1})$
- $B = \pm \alpha \mu_{eff} N_t (\text{cm}^{-1} \text{ eV}^{-1})$
- $C = \alpha^2 \mu_{eff}^2 N_t (\text{cm eV}^{-1})$
- $A = B^2/(4C)$



Independent parameters:

 α and N_t









Modified 1/f noise model that takes into account threshold variation along the channel.

- For simplicity assume two regions:
 - $\Delta V, \Delta L, V_{T2}, A_2, B_2, C_2$
 - $V_{ds} \Delta V, L \Delta L, V_{Tl}, A_l, B_l, C_l$
 - $\Delta L << L, V_T \approx V_{TI}$
 - $-A_1 = A_2$, since $N_{t1} = N_{t2}$
 - $B_1^2/C_1 = B_2^2/C_2 = 4A$
 - $I_1 = I_2 = I_d$
 - $\mu_{eff1} = \mu_{eff2},$



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Independent parameters: N_t , α_1 , α_2 , V_{T2} , and ΔV

Modified 1/f noise model that takes into account threshold variation along the channel.





RTS in MOSFETs

Random Telegraph Signals: single electron switching.





RTS in **MOSFETs**

Random Telegraph Signals (RTS) with a Lorentzian on 1/f spectum.





NMOS,W/L(µm)=5/0.23, VDS=175mV, VGS=0.60V













COMPLEX RTS



Complex random telegraph signals due to multiple traps

$$\frac{S_I(f)}{I^2} \propto \sum_{k=1}^{N_{traps}} \frac{\left(\Delta I/I\right)_k^2}{\left(\overline{\tau}_0 + \overline{\tau}_1\right)_k \left[\left(1/\overline{\tau}_0 + 1/\overline{\tau}_1\right)_k^2 + \left(2\pi f\right)^2\right]}$$



RTS in MOSFETs

RTS can be used to characterize trapping sites.



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RTS in **MOSFETs**

RTS can be used to characterize trapping sites.

- Position of the trap along the channel, y_T
- Position of the trap in the oxide, x_T
- Trap energy, E_{Cox} E_T
- Screened scattering coefficient, α

$$\frac{\Delta I_d}{I_d} = \frac{\Delta N}{N} \pm \frac{\Delta \mu}{\mu} = -\frac{1}{W_{eff}L_{eff}} \left[\frac{1}{N} \pm \alpha \mu\right]$$

$$\ln\frac{\overline{\tau}_c}{\overline{\tau}_e} = -\frac{1}{kT} \left[\left(E_{Cox} - E_T \right) - \left(E_C - E_{F_p} + qV_c \right) - \phi_0 + q\psi_s + q\frac{x_T}{T_{ox}} \left(V_{gs} - V_{FB} - \psi_s \right) \right]$$



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 $V_c \approx y V_{ds} / L$

Trapping Parameters Through RTS in MOSFETs



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Trapping Parameters Through RTS in MOSFETs





Trapping Parameters Through RTS in MOSFETs



$$\alpha = K_1 + K_2 \ln N$$



Effects of Quantization



•Increase in effective energy band-gap: change in τ_e and τ_c

• Shift in carrier distribution: change in C_{ox}



3-D Treatment of RTS

$$\tau_c = \frac{1}{\overline{c}_n \cdot n_{3D}} = \frac{1}{\sigma_n (3D) \cdot V_{th} \cdot n_{3D}}$$

$$\tau_e = \frac{\exp[(E_F - E_T) / k_B T]}{\sigma_n (3D) \cdot V_{th} \cdot n_{3D}}$$

$$\overline{c}_n = \sigma_n (3D) \cdot V_{th}$$



2-D Treatment of RTS - τ_c and τ_e

$$\tau_c = \frac{1}{\overline{c_n} \cdot n_{2D}} \cdot \int_0^{\overline{z}} \frac{p(z)}{\overline{z}} dz = \frac{1}{\sigma_n(2D) \cdot V_{th} \cdot n_{2D}} \cdot \int_0^{\overline{z}} \frac{p(z)}{\overline{z}} dz$$

$$\tau_e = \frac{1}{\overline{e}_n} = \frac{\exp[(E_F - E_T)/k_B T]}{\sigma_n (2D) \cdot V_{th} \cdot n_{2D} \cdot \int_0^{\overline{z}} \frac{p(z)}{\overline{z}} dz}$$

$$\bar{c}_n = \sigma_n (2D) \cdot V_{th}$$



2-D Treatment of RTS

• From Stern - Howard wave-function:

$$p(z) = \frac{b^3}{2} z^2 \exp(-bz)$$

$$b = \left[\frac{12qm_l}{\hbar^2 \varepsilon_{Si} \varepsilon_0} \cdot \left(Q_B + \frac{11}{32} \cdot Q_{inv}\right)\right]^{1/3}$$

$$\overline{z} = 3/b$$



2-D Treatment of RTS

• Calculate the inversion carrier concentration assuming they are located primarily at *E*₀:

$$\frac{1}{N} = \frac{1}{\int n_{2D} \cdot p(z) dz}$$

$$= \left\{ \frac{2k_B T m_t}{\pi \hbar^2} \exp\left[-\left(E_{CS} + \Delta E_0 - E_F\right)/k_B T\right] \cdot \int_0^z p(z) dz \right\}^{-1}$$

$$\Delta E_0 \approx \left(\frac{\hbar^2}{2m_l}\right)^{1/3} \left[\frac{9\pi q}{8\varepsilon_{Si}\varepsilon_0}\right]^{2/3} \left[2\varepsilon_{Si}\varepsilon_0 q N_B (V_{SB} + 2\phi_F)\right]^{1/3}$$



2-D Treatment of RTS - τ_c and τ_e

$$\tau_e = \frac{\exp[(E_{CS} - E_T + \Delta E_0) / k_B T]}{\sigma_n (2D) \cdot V_{th} \cdot (2k_B T m_t b / 5\hbar^2 \pi)}$$

$$\tau_c = \frac{\exp[(E_{CS} - E_F + \Delta E_0) / k_B T]}{\sigma_n (2D) \cdot V_{th} \cdot (2k_B T m_t b / 5\hbar^2 \pi)}$$

$$\ln\left(\frac{\tau_c}{\tau_e}\right) = -\frac{1}{k_B T} \left[\left(E_{Cox} - E_T\right) - \left(E_{CB} - E_F\right) - \phi_0 + q\psi_s + q\frac{z_T}{T_{ox}} \left(V_{gs} - V_{FB} - \psi_s\right) \right]$$

• To first order, the ratio is not affected by quantization.



RTS Measurements

- MDD n-MOSFETs
- $W_{eff} \times L_{eff} = 1.37 \times 0.17 \ \mu m^2$
- $T_{ox} = 4 \text{ nm}$
- $V_T = 0.375$ V for $V_{SB} = 0$ V
- strong inversion, linear region $V_{DS} = 100 \text{ mV}$
- $V_{SB} = 0 0.4 \text{ V}, V_{GS} = 0.5 0.75 \text{ V}$



$$E_{Cox}$$
- E_T and z_T from τ_c and τ_c

$$\ln\left(\frac{\tau_c}{\tau_e}\right) = -\frac{1}{k_B T} \left[\left(E_{Cox} - E_T\right) - \left(E_{CB} - E_F\right) - \phi_0 + q\psi_s + q\frac{z_T}{T_{ox}} \left(V_{gs} - V_{FB} - \psi_s\right) \right]$$





 E_{Cox} - E_T and z_T from τ_c and τ_e



E_{Cox} - E_T and z_T from τ_c and τ_e

$T_{ox} = 4 \text{ nm}$

$V_{SB}(V)$	$V_{T}(V)$	z _T (Å)	E_{Cox} - E_T (eV)
0	0.375	11.22	3.09
0.1	0.382	11.53	3.08
0.2	0.393	11.37	3.08
0.3	0.401	11.64	3.07
0.4	0.408	11.08	3.08







Dependence of τ_c on V_{SB}

$$\tau_c = \frac{\exp[(E_{CS} - E_F + \Delta E_0) / k_B T]}{\sigma_n (2D) \cdot V_{th} \cdot (2k_B T m_t b / 5\hbar^2 \pi)}$$





c_n Extracted from τ_c and τ_e





2-D Treatment of RTS - Amplitude

$$\frac{\Delta I_D}{I_D} = -\left[\frac{1}{\Delta N}\frac{\delta\Delta N}{\delta\Delta N_t} \pm \frac{1}{\mu}\frac{\delta\mu}{\delta\Delta N_t}\right] = \left]\delta\Delta N_t = -\frac{1}{W_{eff} \times L_{eff}} \left(\frac{1}{N} \pm \alpha\mu\right)$$

$$\mu^{-1} = \mu_n^{-1} + \mu_t^{-1} = \mu_n^{-1} + \alpha N_t$$

- Question: How does quantization affect number and mobility fluctuations?
 - Number fluctuation through N
 - Mobility fluctuations through oxide charge scattering, μ_t .



Extraction of Scattering Coefficient

- Mobility Fluctuations:
 - Using Surya's 2D surface mobility fluctuations model,

$$\mu_t^{-1} = \frac{m_n^* q^3}{8\hbar\pi\varepsilon_{av}^2 E_p} \int dz \int dE \int_0^{\pi/2} \frac{\exp(-4kz\sin\phi)\sin^2\phi}{(\sin\phi + \frac{c}{2k})^2} d\phi N_t(E,z)$$

$$k = 0.8 (2\pi/a_{Si})$$

$$c = \frac{2q^2 d_v m_n^*}{4\hbar^2 \pi \varepsilon_{si}} \left\{ 1 - \exp\left[-\left(\frac{\hbar^2 \pi N}{k_B T d_v m_n^*}\right) \right] \right\}$$



Calculation of Scattering Coefficient

• Considering a single trap: $N_t(E,z) = N_t \delta(E-E_T) \times \delta(z-z_T)$





RTS Amplitude





Extraction of Scattering Coefficient





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Extraction of Scattering Coefficient





Possible Reasons for Discrepancy

- Threshold non-uniformity along the channel is not taken into account.
- Location of the trap along the channel
- Variation of the channel voltage from source to drain is neglected.
- $\delta \Delta N / \delta \Delta N_t \approx 1$ is not valid, even in strong inversion, for very thin oxides.



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